

<b>STN</b>	<b>Monokryštalické dosky na súčiastky s povrchovou akustickou vlnou (SAW) Špecifikácia a meracia metóda</b>	<b>STN EN IEC 62276</b>  36 8335
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Single crystal wafers for surface acoustic wave (SAW) device applications - Specifications and measuring methods

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/25

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**EN IEC 62276**

NORME EUROPÉENNE

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April 2025

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English Version

Single crystal wafers for surface acoustic wave (SAW) device  
applications - Specifications and measuring methods  
(IEC 62276:2025)

Tranches monocristallines pour applications utilisant des  
dispositifs à ondes acoustiques de surface (OAS) -  
Spécifications et méthodes de mesure  
(IEC 62276:2025)

Einkristall-Wafer für Oberflächenwellen-(OFW-  
)Bauelemente - Festlegungen und Messverfahren  
(IEC 62276:2025)

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**EN IEC 62276:2025 (E)****European foreword**

The text of document 49/1454/CDV, future edition 4 of IEC 62276, prepared by TC 49 "Piezoelectric, dielectric and electrostatic devices and associated materials for frequency control, selection and detection" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62276:2025.

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IEC 60862-1	NOTE	Approved as EN 60862-1
IEC 60862-2	NOTE	Approved as EN 60862-2
IEC 60862-3	NOTE	Approved as EN 60862-3
IEC 61019-1	NOTE	Approved as EN 61019-1
IEC 61019-2	NOTE	Approved as EN 61019-2
ISO 21920-2	NOTE	Approved as EN ISO 21920-2

## **Annex ZA** (normative)

### **Normative references to international publications with their corresponding European publications**

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60758	2016	Synthetic quartz crystal - Specifications and guidelines for use	EN 60758	2016



IEC 62276

Edition 4.0 2025-03

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Single crystal wafers for surface acoustic wave (SAW) device applications –  
Specifications and measuring methods**

**Tranches monocristallines pour applications utilisant des dispositifs à ondes  
acoustiques de surface (OAS) – Spécifications et méthodes de mesure**





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IEC 62276

Edition 4.0 2025-03

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# NORME INTERNATIONALE

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**Tranches monocristallines pour applications utilisant des dispositifs à ondes  
acoustiques de surface (OAS) – Spécifications et méthodes de mesure**

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**SINGLE CRYSTAL WAFERS FOR SURFACE ACOUSTIC WAVE (SAW)  
DEVICE APPLICATIONS – SPECIFICATIONS AND MEASURING METHODS**

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IEC 62276 has been prepared by IEC technical committee 49: Piezoelectric, dielectric and electrostatic devices and associated materials for frequency control, selection and detection. It is an International Standard.

This fourth edition cancels and replaces the third edition published in 2016. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) The terms and definitions, the technical requirements, sampling frequency, test methods and measurement of transmittance, lightness, colour difference for LN and LT have been added in order to meet the needs of industry development;
- b) The term "inclusion" (mentioned in 4.13 and 6.10) and its definition have been added because there was no definition for it in Clause 3;

- c) The specification of LTV and PLTV, and the corresponding description of sampling frequency for LN and LT have been added, because they are the key performance parameters for the wafers;
- d) The tolerance of Curie temperature specification for LN and LT have been added in order to meet the development requirements of the industry;
- e) Measurement of thickness, TV5, TTV, LTV and PLTV have been completed, including measurement principle and method of thickness, TV5, TTV, LTV and PLTV.

The text of this International Standard is based on the following documents:

Draft	Report on voting
49/1454/CDV	49/1460/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

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## **SINGLE CRYSTAL WAFERS FOR SURFACE ACOUSTIC WAVE (SAW) DEVICE APPLICATIONS – SPECIFICATIONS AND MEASURING METHODS**

### **1 Scope**

This document applies to the manufacture of synthetic quartz, lithium niobate (LN), lithium tantalate (LT), lithium tetraborate (LBO), and lanthanum gallium silicate (LGS) single crystal wafers intended for use as substrates in the manufacture of surface acoustic wave (SAW) filters and resonators.

### **2 Normative references**

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IEC 60758:2016, *Synthetic quartz crystal – Specifications and guidelines for use*

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